



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the Application of

Akihiro MURATA

Application No.: 09/245,288

Filed: February 5, 1999

For: SEMICONDUCTOR APPARATUS SUBSTRATE, SEMICONDUCTOR
APPARATUS, AND METHOD OF MANUFACTURING THEREOF AND
ELECTRONIC APPARATUS

Group Art Unit: 2814

Examiner: D. Graybill

Docket No.: 101937

#19/E
1-17-02
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AMENDMENT

Director of the U.S. Patent and Trademark Office
Washington, D.C. 20231

Sir:

In reply to the Office Action mailed October 11, 2001, please amend the above-
identified Application as follows:

IN THE CLAIMS:

Please replace claims 1-4 and 6 as follows:

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1. (Amended) A substrate for semiconductor apparatus, comprising:
a substrate main body having a delineated mounting surface for mounting the
semiconductor device;
a plurality of leads formed on the mounting surface, the plurality of lead radially
extending from a peripheral area toward a central area of the substrate main body; and
a plurality of conduction sections each defining at least part of an external terminal
with substantially rectangular contour lines, the conduction sections being electrically
connected to the leads.